

MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

LCD MODULE SPECIFICATION

Model: MI0350BT-5

This module uses ROHS material

For Customer's Acceptance:

| | • |
|----------|---|
| Customer | |
| Approved | |
| Comment | |

This specification may change without prior notice in order to improve performance or quality. Please contact Multi-Inno for updated specification and product status before design for this product or release of this order.

| Revision | 1.1 |
|---------------|------------|
| Engineering | |
| Date | 2013-11-05 |
| Our Reference | |



REVISION RECORD

| REV NO. | REV DATE | CONTENTS | REMARKS |
|---------|------------|----------------------------------|---------|
| 1.0 | 2012-06-26 | First release | |
| 1.1 | 2013-11-05 | Correct supply voltage parameter | |
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■ GENERAL INFORMATION

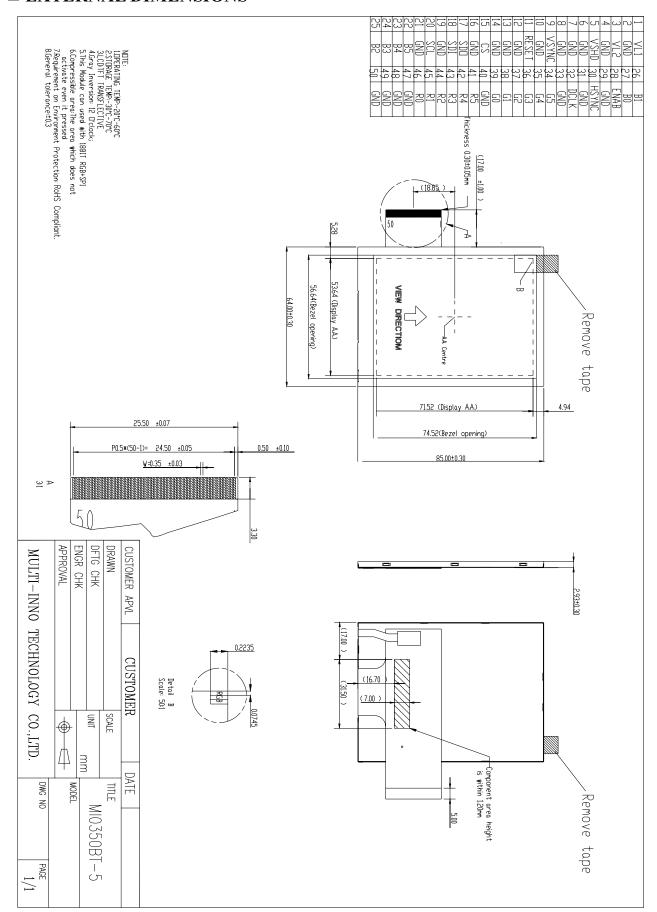
| Item | Contents | Unit/Note |
|---------------------------------|--|-----------|
| LCDtype | TFT/Transflective | / |
| Size | 3.5 | Inch |
| Viewing direction | 6:00 (without image inversion and least brightness change) | O'Clock |
| Gray scale inversion direction | 12:00(contrast peak located at) | O'Clock |
| Module area (W × H) | 64.00×85.00x2.93 | mm^2 |
| Active area (W×H) | 53.64×71.52 | mm^2 |
| Number of Dots | 240(RGB)×320 | / |
| Pixel pitch($W \times H$) | 0.2235×0.2235 | mm^2 |
| Colors | 262K | / |
| Surface treatment(Up polarizer) | HC | / |
| Driving IC | ILI9341 | / |
| Backlight Type | 6LEDs | / |
| InterfaceType | RGB 18 bit+SPI | / |
| Input voltage | 2.8 | V |
| Weight | 33.5 | g |
| With/Without TSP | Without TSP | / |

Note 1: Viewing direction for best image quality is different from TFT definition, there is a 180 degree shift. Note 2: RoHS compliant;

Note 3: LCM weight tolerance: \pm 5%.



■ EXTERNAL DIMENSIONS





■ABSOLUTE MAXIMUM RATINGS

GND=0V,Ta=25°C

| Item | Symbol | Min | Max | Unit | Remark |
|----------------------------|---------|-------|------------|------------------------|--------|
| Supply Voltage | VSHD | -0.3 | 4.6 | V | |
| Driver supply voltage | VGH-VGL | -0.3 | +32.0 | V | |
| Logic input voltage range | VIN | -0.3 | VSHD + 0.3 | V | |
| Logic output voltage range | VO | -0.3 | VSHD + 0.3 | V | |
| Operating temperature | Тор | -20.0 | 60.0 | $^{\circ}\!\mathbb{C}$ | Note1 |
| Storage temperature | Tst | -30.0 | 70.0 | ${\mathbb C}$ | Note1 |

Note1: The parameter is for driver IC (gate driver, source driver) only.

Note2: Signals include R0~R5, G0~G5, B0~B5, DCLK, Hsync, Vsync, Reset, CS, SDI, SCL, .ENABLE

■ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS

GND=0V. Ta=25°C

| Item | | Symbol | Min | Тур | Max | Unit | Remark |
|------------------------------|------------|-------------------|---------|-------|---------|------|---|
| Supply Voltage | ge | VSHD | 2.5 | 2.8 | 3.3 | V | |
| Gate on volta | age | VGH | 13.5 | 15.0 | 16.5 | V | |
| Gate off volta | age | VGL | -11.0 | -10.0 | -9.0 | V | |
| Input Signal Voltage | Low Level | V_{IL} | 0 | - | 0.3VSHD | V | R0~R5;G0~G5;B0~B5 DOTCLK; Hsync; Vsync |
| | High Level | V_{IH} | 0.7VSHD | - | VSHD | | ENABLE;R/L;U/D |
| Current of VSHD Power supply | | I _{VSHD} | - | 15 | - | mA | Note 1 |

Note1: For different LCM, the value may have a bit of difference. Note2: To test the current dissipation, use "all Black Pattern".

■ BACKLIGHT CHARACTERISTICS

Ta=25℃

| Item | Symbol | Min | Тур | Max | Unit | Remark |
|-----------------------------|----------------|--------|------|-----|------|--------|
| Forward Current | I _F | - | 20 | - | mA | |
| Forward Voltage | V_{BL} | - | 19.2 | - | V | |
| Backlight Power Consumption | W_{BL} | - | 384 | - | mW | |
| Life Time | | 10,000 | - | - | Hrs | Note 3 |

Note 1: I_F is defined for one channel LED. There are total three LED channels in back light unit

Note 2: Optical performance should be evaluated at Ta=25^o only.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.

Table 4.2 LED backlight characteristics

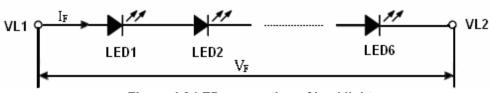


Figure 4.2 LED connection of backlight



MODULE NO.: MI0350BT-5 Ver 1.1

■ELECTRO-OPTICAL CHARACTERISTICS

DRIVING THE BACKLIGHT CONDITION

| Item | Symbol | Condition | Min | Тур | Max | Unit | Remark | Note |
|-------------------------|---------|-------------------|-----|-------|-----|-------------------|--------|------|
| Response time | Tr +Tf | θ=0° | - | 35 | - | ms | Fig.1 | 4 |
| Contrastratio | Cr | Ø=0° | 100 | 150 | - | | FIG 2. | 1 |
| Surface Luminance | Lv | Ta=25℃ | 60 | 100 | - | cd/m ² | FIG 2. | 2 |
| | θ | Ø = 90° | 55 | 60 | - | deg | FIG 3. | |
| Viewing angle range | | Ø = 270° | 40 | 45 | - | deg | FIG 3. | 6 |
| viewing angle range | | $\emptyset = 0$ ° | 45 | 50 | • | deg | FIG 3. |] " |
| | | Ø = 180° | 40 | 45 | ı | deg | FIG 3. | |
| CIE (x, y) chromaticity | White x | T. 05°C | - | 0.293 | - | | FIG 2. | 5 |
| | White y | Ta=25℃ | - | 0.307 | - | | | |

NOT DRIVING THE BACKLIGHT CONDITION

| Item | Symbol | Condition | Min | Тур | Max | Unit | Remark | Note |
|-------------------------|---------|-------------------|-----|-------|-----|------|--------|------|
| Contrastratio | Cr | Ø=0° | - | 6.5 | - | | FIG 2. | 1 |
| Reflectance | | Ta=25℃ | - | 7.0 | - | % | FIG 2. | 3 |
| | θ | Ø = 90° | - | 60 | - | deg | FIG 3. | |
| Viewing angle range | | Ø = 270° | - | 60 | - | deg | FIG 3. | 6 |
| viewing angle range | | $\emptyset = 0$ ° | - | 60 | • | deg | FIG 3. |] 0 |
| | | Ø = 180° | - | 55 | • | deg | FIG 3. | |
| CIE (x, y) chromaticity | White x | E 25°C | - | 0.310 | - | · | FIG 2. | 5 |
| | White y | Ta=25℃ | - | 0.320 | - | | | |

Test Conditions:

- 1. I_F = 20mA, V_F =19.2V, the ambient temperature is 25°C.
- The test systems refer to Note 1 and Note 2.

Note 1. Contrast Ratio(CR) is defined mathematically as For more information see FIG 2.:

Contrast Ratio =
$$\frac{\text{Average Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}{\text{Average Surface Luminance with all black pixels } (P_1, P_2, P_3, P_4, P_5)}$$

Note 2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels $(P_1, P_2, P_3, P_4, P_5)$

Note 3. The uniformity in surface luminance, δ WHITE is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$$\delta \text{ WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}{\text{Maximum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}$$

Note 4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1. The test equipment is Autronic-Melchers's ConoScope. Series

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Note 5. CIE (x, y) chromaticity, The x,y value is determined by measuring luminance at each test position 1 through 5, and then make average value

Note 6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the conrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note 7. For Viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments. For contrast ratio, Surface Luminance, Luminance uniformity, CIE The test data is base on TOPCON's BM-5 photo detector.

Note 8. For TFT module, Gray scale reverse occurs in the direction of panel viewing angle.

FIG.1. The definition of Response Time

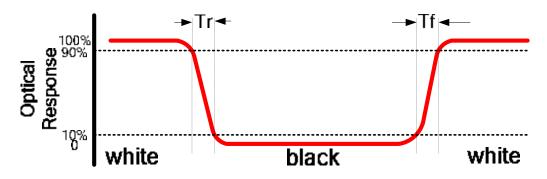


FIG.2. Measuring method for Contrast ratio, surface luminance, Luminance uniformity, CIE (x, y) chromaticity

A:5 mm B:5 mm

H,V: Active Area

Light spot size ∅=5mm, 500mm distance from the LCD surface to detector lens

measurement instrument is TOPCON's luminance

meter BM-5

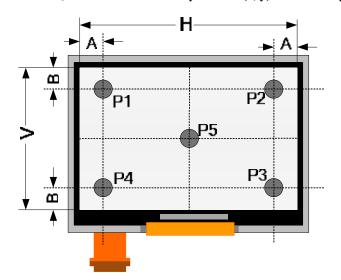
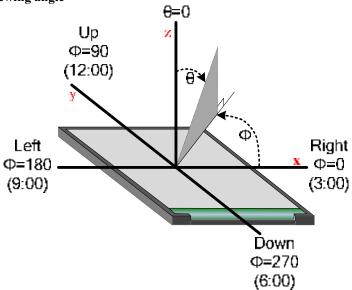




FIG.3. The definition of viewing angle





■ INTERFACE DESCRIPTION

1 J1 Pin Assignment

Connector type: FH12A-50S-0.5SH

| No | Symbol | I/O | Description | Comment |
|----|--------|----------|------------------------------------|---------|
| 1 | VL1 | Р | Power supply for LED(High voltage) | |
| 2 | GND | P | Ground | |
| 3 | VL2 | Р | Power supply for LED(Low voltage) | |
| 4 | GND | Р | Ground | |
| 5 | VSHD | Р | Power supply for digital | |
| 6 | GND | Р | Ground | |
| 7 | GND | Р | Ground | |
| 8 | GND | Р | Ground | |
| 9 | VSYNC | I | Vertical sync. in RGB mode | |
| 10 | GND | Р | Ground | |
| 11 | RESET | I | Reset(Low active) | |
| 12 | GND | Р | Ground | |
| 13 | GND | Р | Ground | |
| 14 | GND | Р | Ground | |
| 15 | CS | I | Chip select input(Low enable) | |
| 16 | GND | Р | Ground | |
| 17 | SDO | 0 | Serial data output | |
| 18 | SDI | I | Serial data input | |
| 19 | GND | Р | Ground | |
| 20 | SCL | I | Serial interface clock | |
| 21 | GND | Р | Ground | |
| 22 | B5 | I | Blue data input(MSB) | |
| 23 | B4 | I | Blue data input | |
| 24 | B3 | I | Blue data input | |
| 25 | B2 | I | Blue data input | |
| 26 | B1 | I | Blue data input | |
| 27 | B0 | I | Blue data input(LSB) | |
| 28 | ENAB | I | Data enable in RGB mode | |
| 29 | GND | Р | Ground | |
| 30 | HSYNC | I | Horizontal sync. in RGB mode | |
| 31 | GND | Р | Ground | |
| 32 | DCLK | | Pixel clock signal in RGB mode | |
| 33 | GND | Р | Ground | |
| 34 | G5 | l | Green data input(MSB) | |
| 35 | G4 | I | Green data input | |
| 36 | G3 | l | Green data input | |
| 37 | G2 | | Green data input | |
| 38 | G1 | <u> </u> | Green data input | |
| 39 | G0 | l | Green data input(LSB) | |
| 40 | GND | Р | Ground | |
| 41 | R5 | l | Red data input(MSB) | |
| 42 | R4 | l | Red data input | |
| 43 | R3 | l | Red data input | |
| 44 | R2 | | Red data input | |

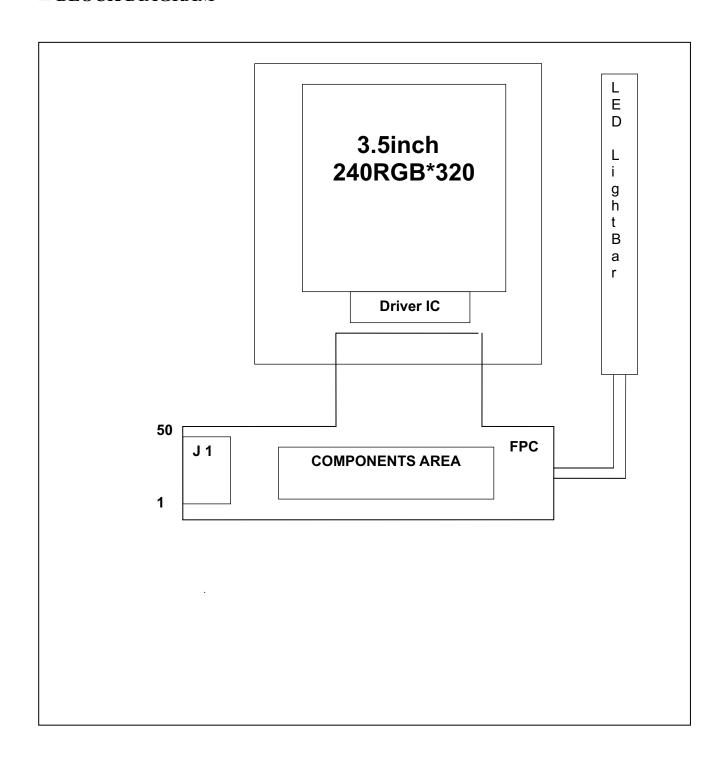


| 45 | R1 | I | Red data input | |
|----|-----|---|---------------------|--|
| 46 | R0 | I | Red data input(LSB) | |
| 47 | GND | Р | Ground | |
| 48 | GND | Р | Ground | |
| 49 | GND | Р | Ground | |
| 50 | GND | Р | Ground | |

Note1: I/O definition:

I----Input O----Output P----Power/Ground

■ BLOCK DIAGRAM





■ APPLICATION NOTES

1. Data input timing

1.1 Signal AC Timing

(VSHD=2.5~3.2V,Ta=25°C)

| Signal | Symbol | Parameter | min | max | Unit |
|---------|-------------------------|-----------------------------------|-----|-----|------|
| VSYNC / | t _{SYNCS} | VSYNC/HSYNC setup time | 15 | - | ns |
| HSYNC | tsynch | VSYNC/HSYNC hold time | 15 | - | ns |
| DE | t _{ENS} | DE setup time | 15 | - | ns |
| DE | t _{ENH} | DE hold time | 15 | - | ns |
| D[17:0] | t _{POS} | Data setup time | 15 | - | ns |
| D[17:0] | t _{PDH} | Data hold time | 15 | - | ns |
| | PWDH | DOTCLK high-level period | 15 | - | ns |
| DOTOLK | PWDL | DOTCLK low-level period | 15 | - | ns |
| DOTCLK | t _{CYCD} | DOTCLK cycle time | 100 | - | ns |
| | t_{rgbr} , t_{rgbf} | DOTCLK,HSYNC,VSYNC rise/fall time | ı | 15 | ns |

Table 1.1 RGB Interface Characteristics

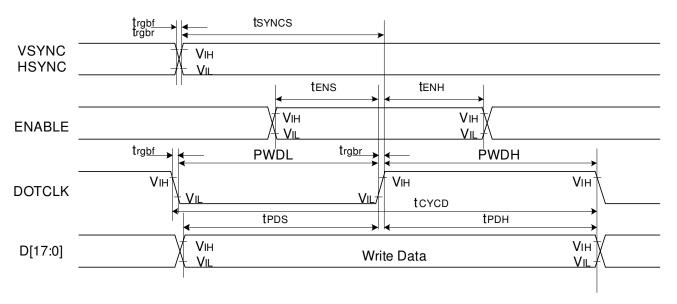


Fig.1-1 RGB Interface Timing

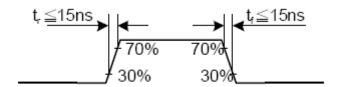


Fig.1-2 Input signal's rise and fall times

1.2 Recommend RGB Interface Timing

(VSHD=2.5~3.2V,Ta=25°C)

| Parameter | Symbol | Symbol | Min | Тур | Max | Unit | Remark |
|-----------|------------------------|--------|-----|--------|-----|-------|--------|
| DCLK | DCLK frequency | fDCYC | - | 5.64 | 10 | MHz | |
| DOLK | DCLK period | tDCYC | 100 | 177.15 | - | ns | |
| | Horizontal | Thd | | 240 | | | |
| HSYNC | 1horizontalline | Th | - | 310 | - | DCLK | |
| 1101110 | Horizontal blank | Thb | 56 | 60 | - | DOLK | |
| | Horizontal front porch | Thfp | 2 | 10 | 16 | | |
| | Vertical display area | Tvd | | 320 | | | |
| VSYNC | Vsync period time | Tv | - | 328 | - | Line | |
| VSTNC | Vsync blank | Tvb | 2 | 4 | - | Lille | |
| | Vsync Front porch | Tvfp | 2 | 4 | - | | |

Tab.1-2 Recommend Input Timing (DCLK, HSYNC, VSYNC, ENAB)

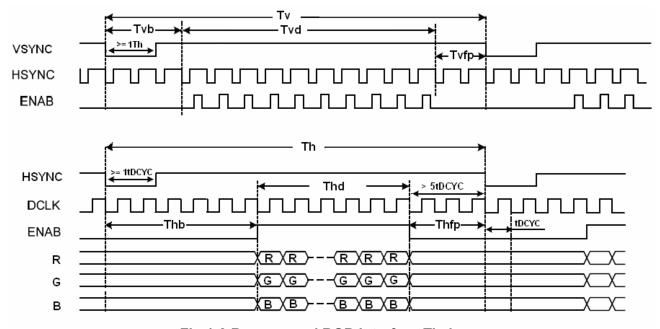


Fig.1-3 Recommend RGB Interface Timing

1.2 3-Wire 9-BIT Serial Interface

1.2.1 3-Wire 9-Bit data serial interface write mode

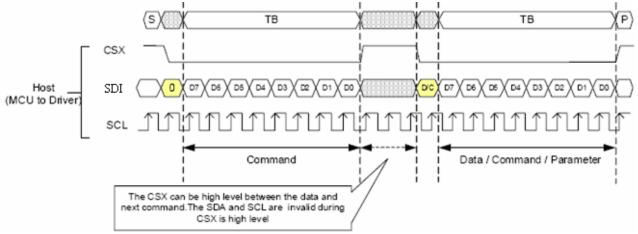


Figure. 1-4 3-Wire 9-Bit Serial Interface I Bus Protocol, Write to Register or Display RAM Note: D/C =0, Transfer Command; D/C =1, Transfer Data.

1.2.2 3-Wire 9-Bit data serial interface read 1-byte mode

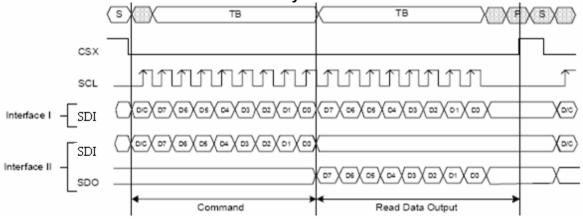


Figure. 1-5 3-Wire 9-Bit Serial Interface I/II Bus Protocol, Read 1-Byte From Register Note: D/C=0, Transfer Command; D/C=1, Transfer Data.



1.2.3 3-Wire 9-Bit data serial interface read 3-byte mode

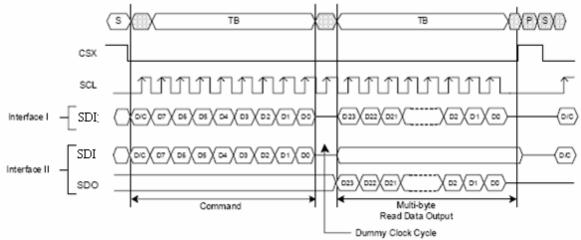


Figure. 1-6 3-Wire 9-Bit Serial Interface I/II Bus Protocol, Read 3-Byte From Register Note: D/C=0, Transfer Command; D/C=1, Transfer Data.

1.2.4 3-Wire 9-Bit serial interface Timing

(VSHD=2.5~3.2V,Ta=25°C)

| Parameter | Symbol | Conditions | Min | Max | Unit | Remark |
|----------------------------|--------|------------|-----|-----|------|--------|
| Serial Clock Cycle(Write) | tscycw | SCL | 100 | - | ns | |
| SCL "H" pluse width(Write) | tshw | SCL | 40 | - | ns | |
| SCL "L" pluse width(Write) | tslw | SCL | 40 | - | ns | |
| Data setup time(Write) | tsds | SDI | 30 | - | ns | |
| Data hold time(Write) | tsdh | SDI | 30 | - | ns | |
| Serial Clock Cycle(Read) | tscycr | SCL | 150 | - | ns | |
| SCL "H" pluse width(Read) | tshr | SCL | 60 | - | ns | |
| SCL "L" pluse width(Read) | tslr | SCL | 60 | - | ns | |
| Access time | tacc | SDO(Read) | 10 | | ns | |
| Output disable time | toh | SDO(Read) | 10 | 50 | ns | |
| CS "H" pluse width | tchw | CS | 40 | - | ns | |
| CS-SCL time | tcss | CS (Write) | 60 | - | ns | |
| CO-SCL time | tcsh | CS (Write) | 65 | - | ns | |

Tab.1-3 AC Characteristics of 3-Wire 9-Bit Serial Interface



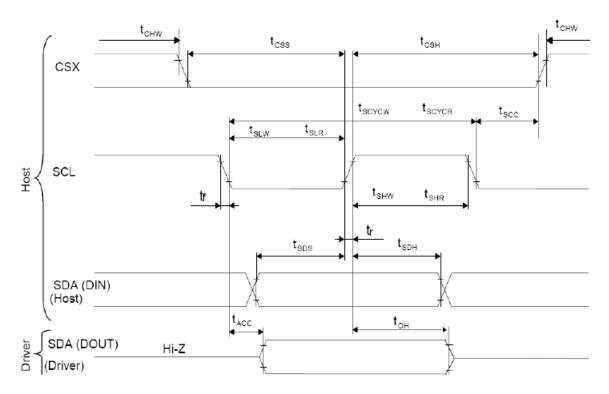


Fig.1-7 AC Characteristics of 3-Wire 9-Bit Serial Interface timing

1.3 Reset Timing

| Parameter | Symbol | MIN | TYP | MAX | Unit | Remark |
|-----------|--------|-----|-----|-----|------|--------|
| | tRW | 10 | - | ı | us | - |
| RESET | tRT | - | - | 5 | ms | note 1 |
| | uxi | - | - | 120 | ms | note 2 |

Tab.1-4 Reset input timing

Note1: When Reset applied during Sleep In Mode. Note2: When Reset applied during Sleep Out Mode.

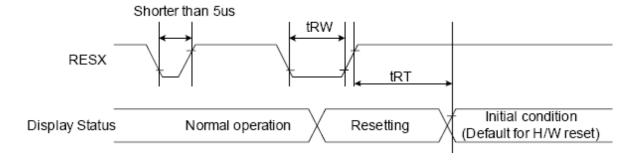


Fig.1-8 Reset timing

1.5 Power ON/OFF Sequence

| Item | Symbol | Min | Тур | Max | Unit | Remark |
|---|--------|-----|-----|-----|------|--------|
| VSHD to RESET2 ending/ RESET2 starting to VSHD | t1 | 10 | | | ms | |
| RESET2 ending to SPI starting/ SPI ending to RESET2 starting | t2 | 10 | - | 50 | ms | |
| SPI starting to RGB starting/ RGB ending to SPI ending | t3 | 20 | - | 50 | ms | |
| RGB starting to BLU starting/ BLU ending to RGB ending | t4 | 50 | - | - | ms | |
| RGB ending to RESET1 starting | t5 | 20 | - | - | ms | |

Table 5.5 Power on/off sequence

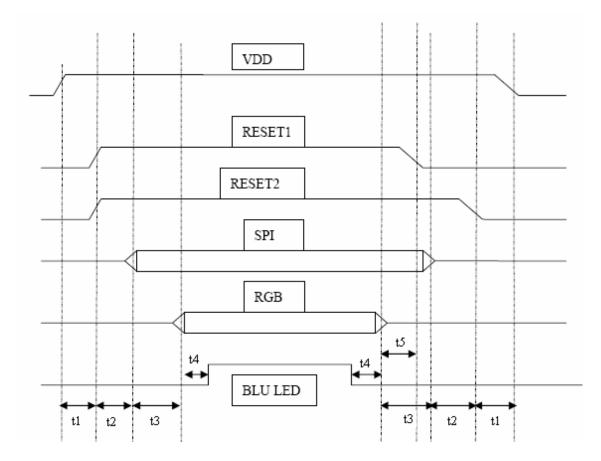


Figure 1.5 Power on/off sequence

Note1:RESET1Power down in sleep out mode. Note2:RESET2 Power down in sleep in mode.



■ RELIABILITY TEST

| No. | Test Item | Test Condition | Remark |
|-----|-----------------------------------|---|--|
| 1 | High Temperature Storage | 80 ± 2 °C/240 hours | IEC60068-2-1 GB2423.2 |
| 2 | Low Temperature Storage | -30±2°C/240 hours | IEC60068-2-1 GB2423.1 |
| 3 | High Temperature Operating | 60±2°C/240 hours | IEC60068-2-1 GB2423.2 |
| 4 | Low Temperature Operating | -20 ± 2 °C/240 hours | IEC60068-2-1 GB2423.1 |
| 5 | Temperature Cycle storage | $-30\pm2^{\circ}\text{C}\sim25\sim70\pm2^{\circ}\text{C}\times20\text{cycles}$ (30min.) (5min.) (30min.) | Start with cold temperature, End with high temperature, IEC60068-2-14 GB2423.22 |
| 6 | Damp proof Test operating | $40^{\circ}\text{C} \pm 5^{\circ}\text{C} \times 90\%\text{RH}/240 \text{ hours}$ | IEC60068-2-78 GB/T2423.3 |
| 7 | Vibration Test (non-operation) | Frequency range:10Hz~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2hours for each direction of X,Y,Z(6 hours for total) | IEC60068-2-6 GB/T2423.10 |
| 8 | Package drop test | Height:60cm,1 corner,3 edges,6 surfaces | IEC60068-2-32,GB2423.8 |
| 9 | ESD test (operation) | C=150pF,R=330 Ω,5points/panel Air: ±8KV,5times Contact: ±4KV,5times(Environment: 15°C~35°C,30%~60%,86Kpa~106Kpa) | IEC61000-4-2 GB/T17626.2 |
| 10 | Shock(non-operation) | 100G 6ms, ±X, ±Y, ±Z 3times each direction | IEC60068-2-27 GB/T2423.5 |

Note 1:Ts is the temperature of panel's surface. Note 2:Ta is the ambient temperature of sample.



■ INSPECTION CRITERION

| OUTGOING QUALITY STANDARD | PAGE 1 OF 7 |
|---|-------------|
| TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA | |

This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM with touch panel.

1 Sample plan

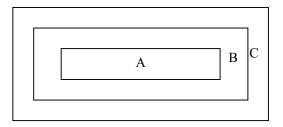
Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65 Minor defect: AQL 1.5

2. Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45° against perpendicular line.

3. Definition of inspection zone in LCD.



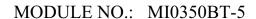
Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.







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TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA

4. Inspection standards

4.1 Major Defect

| Item No | Items to be inspected | Inspection Standard | Classification of defects |
|------------|------------------------------|--|---------------------------|
| 4.1.1 | All functional defects | No display Display abnormally Missing vertical, horizontal segment Short circuit Back-light no lighting, flickering and abnormal lighting. | |
| 4.1.2 | Missing | Missing component | Major |
| 4.1.3 | Outline dimension | Overall outline dimension beyond the drawing is not allowed. | |
| 4.1.4 | linearity | No more than 1.5% | |

4.2 Cosmetic Defect

| Item No | Items to be inspected | | Inspection | on Standard | | Classification of defects | |
|------------|-----------------------------------|---|--------------------|--------------|----------|---------------------------|--|
| | Clear Spots Black and white Spot | For dark/white spot, as $\Phi = \frac{(x+y)}{2}$ 1. | | | y y | | |
| | defect | Size(mm) | | Acceptable (| | | |
| | Pinhole, | Size(min) | A | В | С | Minor | |
| | Foreign | Ф≤0.1 | Igr | nore | | | |
| | Particle, | 0.10< Ф ≤ 0.15 | 2 | | - Ignore | | |
| | polarizer Dirt | $0.15 < \Phi \le 0.20$ | 1 | | | | |
| 4.2.1 | | 0.20<Ф | | 0 | | | |
| | | 2. | | | | | |
| | | Zone | one Acceptable Qty | | Qty | | |
| | | Size(mm) | A | В | С | | |
| | Clear Spots | Ф ≤ 0.1 | Igı | Ignore | | Minan | |
| | TP Dirt | 0.10<Φ≤0.15 | | 3 | - Ignore | Minor | |
| | | $0.15 < \Phi \le 0.25$ | 2 | | 1511010 | | |
| | | 0.25<Ф | | 0 | | | |
| | | | | | | | |





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| | 3. | | | | | | |
|----------------------|-------------|-----|---------------|--------|---|------|---|
| Dim Spots | 2. Zone | | Acceptable Qt | ty | | | 1 |
| Dim Spots | Size(mm) | A | В | С | | | |
| Circle | Ф ≤0.2 | Igı | nore | | M | inor | |
| shaped and dim edged | 0.20<Ф≤0.40 | | 2 | Innana | | | |
| defects | 0.40<Φ≤0.60 | | 1 | Ignore | | | |
| | 0.60<Ф | | 0 | | | | |

4.2 Cosmetic Defect

| Item No | Items to be inspected | | Inspection Standard Classification of defects | | | | | | |
|------------|------------------------|---|--|------|--------------------|--------------|---|--|--|
| | | S | ize(mm) | 1 | Acceptable | Qty | | | |
| | Line defect | I (I an ath) | W/(W/: J41.) | ZC | | | | | |
| | Black line, | L(Length) | W(Width) | A | В | С | | | |
| | White line, Foreign | Ignore | W≤0.02 | Ig | nore | | | | |
| | material on polarizer | L≤3.0 | 0.02 <w≤0.03< td=""><td></td><td>2</td><td></td><td></td></w≤0.03<> | | 2 | | | | |
| | | L≤2.0 | 0.03 <w≤0.05< td=""><td></td><td>1</td><td>Ignore</td><td></td></w≤0.05<> | | 1 | Ignore | | | |
| | | | 0.05 <w< td=""><td></td><td>e as spot efect</td><td>1</td><td></td></w<> | | e as spot efect | 1 | | | |
| 4.2.2 | | The line can be seen after mobile phone in the operation: | | | perating | Minor | | | |
| | | si | ze(mm) | A | .cceptable (| Qty | | | |
| | Foreign | L(Length) | W(Width) | zone | | | | | |
| | material on TP film | L(Length) | w (widii) | A | В | С | | | |
| | | Ignore | W≤0.03 | Ign | nore | | | | |
| | | L≤5.0 | 0.03 <w≤ 0.05</w≤ | | 3 | Ignore | | | |
| | | | 0.05 <w< td=""><td></td><td></td></w<> | | | | | | |
| | | assembling | If the scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 4.2.2. | | | | | | |
| | | | h can be seen on al angle, judge by | | | condition or | r | | |





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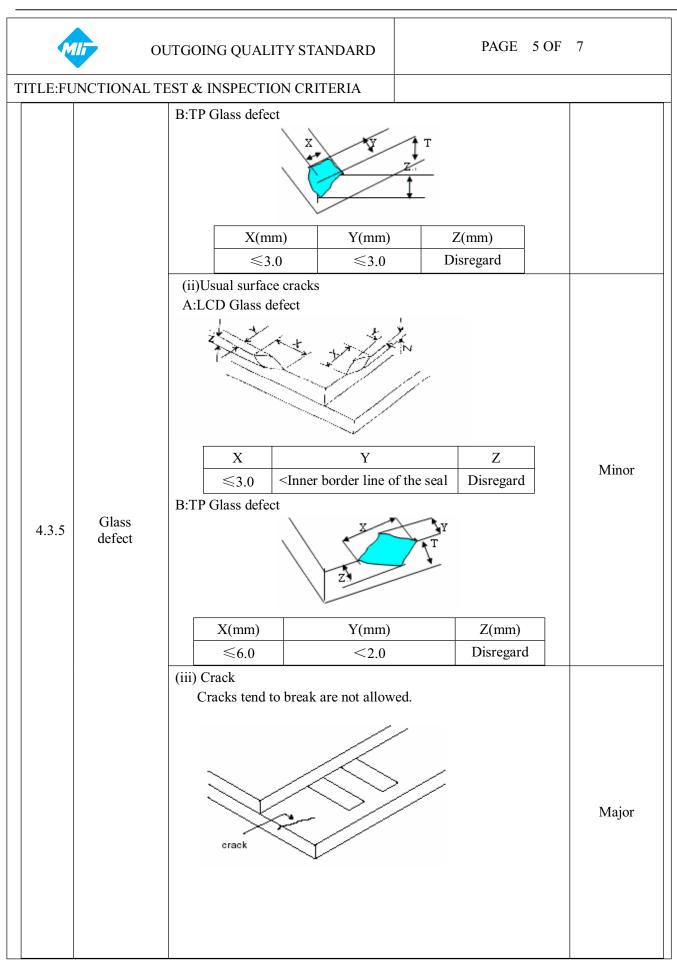
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA

| | Dim line | Size | e(mm) | A | ccepta | ıble Qty | | | | |
|-------|------------------------|---|--|-------------|--|----------|---|----------|--|--|
| | defect | defect L(Length) | | | Zone | | | | | |
| | Polarizer | L(Longin) | W(Width) | A | В | С | | | | |
| 4.2.3 | scratch TP film | Ignore | W≤0.03 | Ign | ore | | | Minor | | |
| | scratch | 5.0 <l≤10.0< td=""><td>0.03<w≤0.05< td=""><td>2</td><td>2</td><td colspan="2">Ignora</td><td></td></w≤0.05<></td></l≤10.0<> | 0.03 <w≤0.05< td=""><td>2</td><td>2</td><td colspan="2">Ignora</td><td></td></w≤0.05<> | 2 | 2 | Ignora | | | | |
| | | | | L≤5.0 | 0.05 <w≤0.08< td=""><td></td><td>1</td><td>- Ignore</td><td></td><td></td></w≤0.08<> | | 1 | - Ignore | | |
| | | | 0.08 <w< td=""><td>(</td><td>0</td><td></td><td></td><td></td></w<> | (| 0 | | | | | |
| | | Air bubbles betw | een glass & polariz | zer | | | | | | |
| | | 2. Zone | Acc | eptable Qty | | | | | | |
| | | Size(mm) | A | В | | С | | | | |
| 4.2.4 | Polarize Air bubble | Ф ≤0.2 | Ignore | ; | | | | Minor | | |
| | | 0.20< Ф ≤ 0.30 | 2 | | | Iomana | | | | |
| | | 0.30< Ф ≤ 0.50 |) 1 | | | Ignore | | | | |
| | | 0.50<Ф | 0 | | | | | | | |

4.3. Cosmetic Defect

| Item No | Items to be inspected | I | Inspection Standard | | | | |
|------------|-----------------------|---|--|----------------|--|-------|--|
| | | (i) Chips on corner A:LCD Glass defect | | | | Minor | |
| | | X ≤2.0 | Y ≪S | Z Disregard | | | |
| | | Notes: S=contact pa | Notes: S=contact pad length hips on the corner of terminal shall not be allowed to extend into the ITO pad or expose perimeter seal. | | | | |











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TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA

4.4 Parts Defect

| Item No | Items to be inspected | Inspection Standard | Classification of defects | |
|------------|----------------------------|--|---------------------------|--|
| | 4.4.1 Parts contraposition | Not allow IC and FPC/heat-seal lead width is more than 50% beyond lead pattern. Not allow chip or solder component is off center more than 50% of the pad outline. | Major | |
| | 4.4.2 SMT | According to the Acceptability of electronic assemblies IPC-A-610C class 2 standard. Component missing or function defect are Major defect, the others are Minor defect. | | |

MODULE NO.: MI0350BT-5 Ver 1.1

■ PRECAUTIONS FOR USING LCD MODULES

Handing Precautions

- (1) The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it
- (2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- (3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).
- (4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.
- (5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents
 - Isopropyl alcohol
 - Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

- (6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
 - Water
 - Ketone
 - Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

- (7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- (8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
 - (9) Do not attempt to disassemble or process the LCD module.
 - (10) NC terminal should be open. Do not connect anything.
 - (11) If the logic circuit power is off, do not apply the input signals.
- (12) Electro-Static Discharge Control, Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
- Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded. make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated
- (13) Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.
 - Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
 - Do not damage or modify the pattern writing on the printed circuit board.
 - Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
 - Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
 - Do not drop, bend or twist LCM.



Handling precaution for LCM

LCM is easy to be damaged. Please note below and be careful for handling. Correct handling:





As above picture, please handle with anti-static gloves around LCM edges.

Incorrect handling:



Please don't touch IC directly.



Please don't stack LCM.



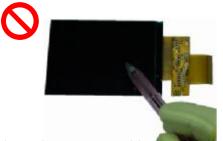
Please don't hold the surface of panel.



Please don't stretch interface of output, such as FPC cable.



Please don't hold the surface of IC.



Please don't operate with sharp stick such as pens.



Storage Precautions

When storing the LCD modules, the following precaution is necessary.

- (1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.
- (2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.
- (3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the anti-static electricity container in which they were shipped.

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
- -Terminal electrode sections.

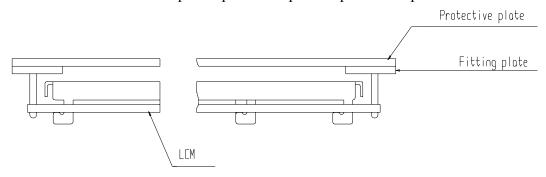


■ USING LCD MODULES

Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

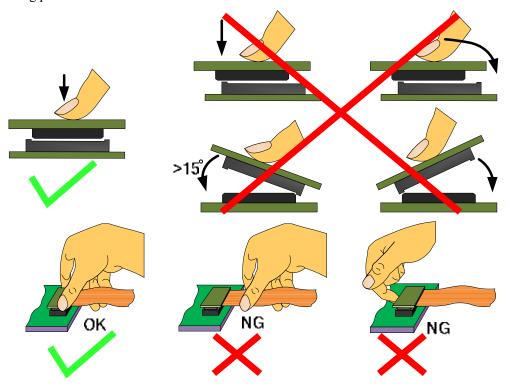
(1) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



(2) When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ± 0.1 mm.

Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position, don't assemble or assemble like the method which the following picture shows



Precaution for soldering the LCM

| | Manual soldering | Machine drag soldering | Machine press soldering |
|---------|------------------|------------------------|-------------------------|
| No RoHS | 290°C ~350°C. | 330°C ~350°C. | 300°C ~330°C. |
| | Time: 3-5S. | Speed: 4-8 mm/s. | Time : 3-6S. |
| product | | | Press: 0.8~1.2Mpa |
| RoHS | 340°C ~370°C. | 350°C ~370°C. | 330°C ~360°C. |
| product | Time: 3-5S. | Time: 4-8 mm/s. | Time : 3-6S. |
| product | | | Press: 0.8~1.2Mpa |





- (1) If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.
- (2) When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- (3) When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

Precautions for Operation

- (1) Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.
- (2) It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- (3) Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, Which will come back in the specified operating temperature.
- (4) If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.
- (5) A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required.
- (6) Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive/negative voltage becomes stable.
- (7) Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.



Safety

- (1) It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
- (2) If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

Limited Warranty

Unless agreed betweenMulti-Inno and customer,Multi-Inno will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with Multi-Inno LCD acceptance standards (copies available upon request) for a period of one year from date of production. Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date shall be based on data code on product. The warranty liability of Multi-Inno limited to repair and/or replacement on the terms set forth above. Multi-Inno will not be responsible for any subsequent or consequential events.

Return LCM under warranty

No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are:

- Broken LCD glass.
- PCB eyelet is damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- Soldering to or modifying the bezel in any manner.

Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet, conductors and terminals.

■ PRIOR CONSULT MATTER

- 1.①For Multi-Inno standard products, we keep the right to change material, process ... for improving the product property without notice on our customer.
 - ②For OEM products, if any change needed which may affect the product property, we will consult with our customer in advance.
- 2. If you have special requirement about reliability condition, please let us know before you start the test on our samples.